



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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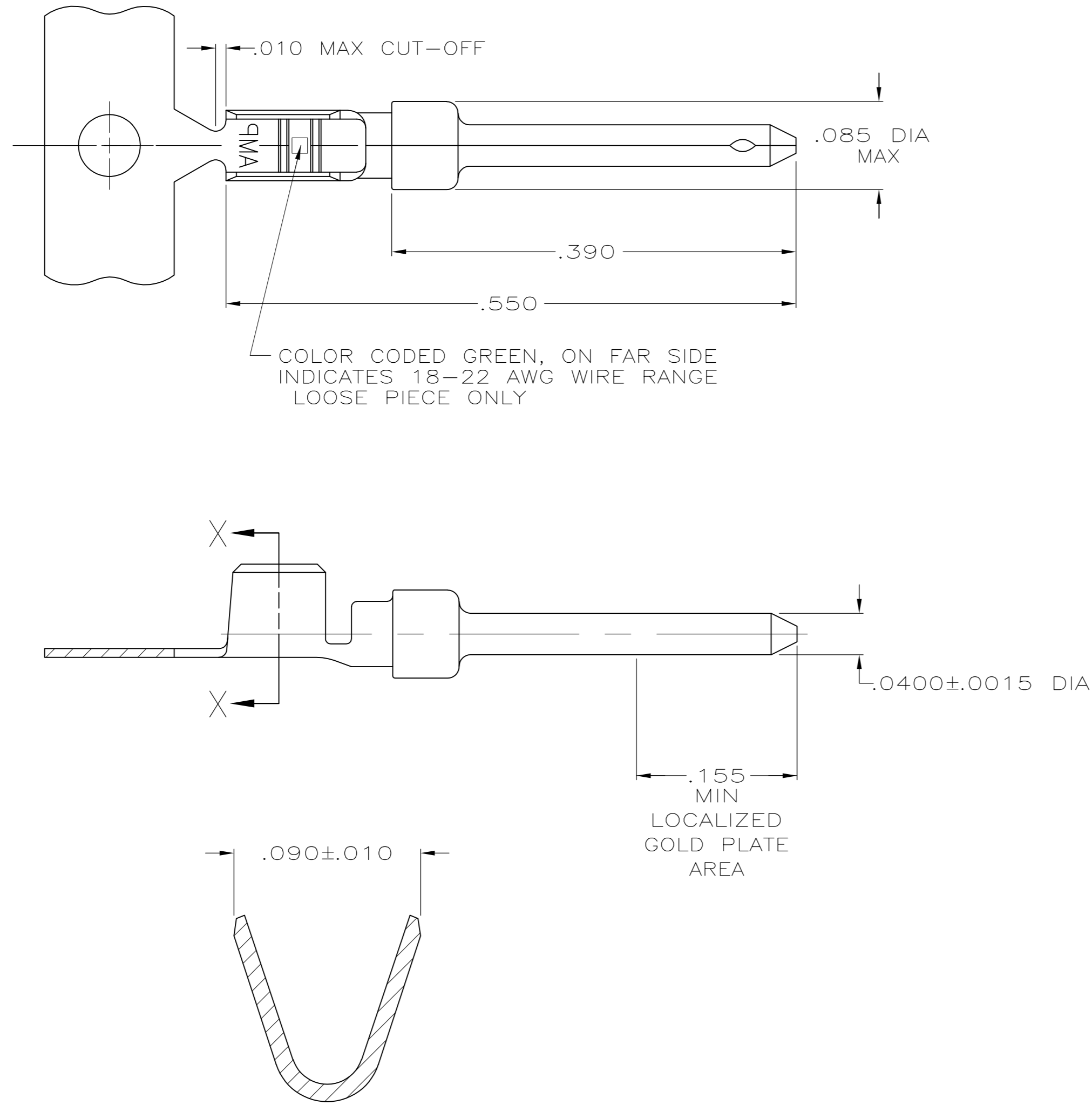
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LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
GP	00				
	K2	REVISED PER ECO-11-017434	19DEC2011	CJV	CWR



SECTION X-X
 WIRE BARREL
 SCALE 20:1

- 1 FOR MINI-APPLICATOR.
- 2 FOR HAND TOOL USE ONLY.
- 3. WIRE RANGE OF 18-22 AWG.
- 4. .068 MAX INSULATION DIAMETER ALLOWABLE WHEN USING 91067-2 EXTRACTION TOOL.
- 5. GOLD PLATING MAY NOT APPEAR ON CARRIER STRIP.
- 6 GOLD PLATING PER MIL-G-45204.
 NICKEL PLATING PER QQ-N-290.
 TIN PLATING PER MIL-T-10727.
- 7 GOLD PLATED IN LOCALIZED GOLD PLATE AREA AS FOLLOWS:
 .000030 MIN GOLD IN MATED AREA,
 GOLD FLASH ON REMAINDER OF CONTACT, ALL OVER .000050
 MIN NICKEL UNDERPLATE.
 OR
 GOLD FLASH OVER
 PALLADIUM-NICKEL PLATE, .000030 MIN TOTAL IN MATED AREA,
 GOLD FLASH ON REMAINDER OF CONTACT, ALL OVER
 .000050 MIN NICKEL UNDERPLATE.
- 8 PLATED WITH GOLD FLASH OVER
 .000050 MIN NICKEL.
- 9 PLATED WITH GOLD FLASH IN LOCALIZED GOLD PLATE AREA,
 TIN PLATED WIRE BARREL, OVER
 .000030 NICKEL.
- 10 GOLD PLATED IN LOCALIZED GOLD PLATE AREA
 .000030 GOLD IN MATED AREA,
 TIN PLATED WIRE BARREL, OVER
 .000050 NICKEL.
- 11 OBSOLETE.
- 12 SUPERSEDED BY 745229-4

10	11-745229-3	11-745229-1
9	11-745229-0	11-745229-8
8	745229-7	745229-5
7	745229-4	745229-2
FINISH 6	LOOSE PIECE 2	PART NUMBER 1

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		MATERIAL		FINISH		MATERIAL		FINISH		MATERIAL		FINISH	
INCHES		SEE TABLE		BRASS PER MIL-C-50		SEE TABLE		114-10000		C=745229		CUSTOMER DRAWING		SCALE 10:1	
0 PLC ± -		1 PLC ± -		2 PLC ± -		3 PLC ± .005		4 PLC ± -		ANGLES ± -		WEIGHT -		SCALE 10:1	
APVD V. KUMAR 9-10-86		APVD V. KUMAR 9-10-86		APVD V. KUMAR 9-10-86		APVD V. KUMAR 9-10-86		APVD V. KUMAR 9-10-86		APVD V. KUMAR 9-10-86		APVD V. KUMAR 9-10-86		APVD V. KUMAR 9-10-86	
S. WELDON 9-9-86		C. RICHARD 9-9-86		S. WELDON 9-9-86		C. RICHARD 9-9-86		S. WELDON 9-9-86		C. RICHARD 9-9-86		S. WELDON 9-9-86		C. RICHARD 9-9-86	
TE Connectivity		TE Connectivity		TE Connectivity		TE Connectivity		TE Connectivity		TE Connectivity		TE Connectivity		TE Connectivity	
PIN CONTACT, SIZE 20 DF, 18-22 AWG, .068 MAX INSULATION DIA		PIN CONTACT, SIZE 20 DF, 18-22 AWG, .068 MAX INSULATION DIA		PIN CONTACT, SIZE 20 DF, 18-22 AWG, .068 MAX INSULATION DIA		PIN CONTACT, SIZE 20 DF, 18-22 AWG, .068 MAX INSULATION DIA		PIN CONTACT, SIZE 20 DF, 18-22 AWG, .068 MAX INSULATION DIA		PIN CONTACT, SIZE 20 DF, 18-22 AWG, .068 MAX INSULATION DIA		PIN CONTACT, SIZE 20 DF, 18-22 AWG, .068 MAX INSULATION DIA		PIN CONTACT, SIZE 20 DF, 18-22 AWG, .068 MAX INSULATION DIA	
SIZE A2		CAGE CODE 00779		DRAWING NO C=745229		RESTRICTED TO -		SCALE 10:1		SHEET 1 of 1		REV K2			